BOND SHEET HTG 3,2W Tg 180°C Low CTE

BONDSHEET CURED HTG®

DELIVERY FORM

PREPREG STORAGE

In cut to size sheets upon request.

PROCESS RECOMMENDATIONS

METAL SURFACE PREPARATION

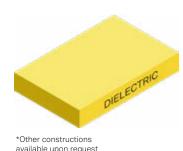
temperature cycle is 1 hour of material temperature over 190°C.

It is the responsibility of the user to ensure that the product complies with his requirements

Data Sheet DS_42

2 2/

STANDARD CONSTRUCTION



Isolation thickness µm (mils) 70 (2,8) 80 (3,1) 100 (3,9) Dielectric thickness tolerance + 10µm (+/- 0,4 mils)

DESCRIPTION

High Tg - B-stage dielectric prepreg glass reinforced with high thermal conductivity. It is based on epoxy ceramic chemistry, and intended for effective bonding between multilayer circuits (PCB) and metal heat spreaders. Its high dielectric strength and resistance to thermal shocks added to its high thermal conductivity assures effective heat dissipation in critical power circuitry. Its low CTE value is ideal to achieve excellent interconnect reliability over thermal cycles.





UL Approved QMTS2 File: E47820 IPC-4101



RoHS 3 / REACH Last updated compliance directive



PROPERTIES	GUARANTEED VALUES		UNITS	TOLERANCE	
	А	В	С		
Nominal thickness (pressed)	70 (2,8)	80 (3,15)	100 (4,0)	µm (mils)	+/- 10µm (0,4mils)
Area weight	145 (203)	185 (259)	225 (315)	g/m² (Lb/mils²)	+/- 10g/m² (14 Lb/mils²)
Glass fabric 106	24,4 (34,8)	24,4 (34,8)	-	g/m² (Lb/mils²)	+/- 1,0g/m² (1,4 Lb/mils²)
Glass fabric 1078	-	-	46,8 (66,4)	g/m² (Lb/mils²)	+/- 2,0g/m² (2,8 Lb/mils²)
Prepreg shelf life (see storage recommendations)	3	3	3	months	-

PREPREG once applied (1)	VALUES	UNITS	TEST METHOD
Time to blister at 288°C, floating solder bath	60	sec	IEC-61189
Copper Peel strength Cu70 µm (2oz)	>1,0 (>5,7)	N/mm (Lb/in	IPC-TM 650-2.4.8
Thermal conductivity (resin)	3,00 (0,076)	W/mK (W/inK	ASTM D5470
Comparative tracking index (CTI)	≥600	V	IEC-61112
Thermal impedance (dielectric layer) HTC 70µm	0,23 (0,036)**	Kcm ² /W (Kin ² /W)	ASTM D5470
Thermal impedance (dielectric layer) HTC 80µm	0,27 (0,042)**	Kcm²/W (Kin²/W)	ASTM D5470
Thermal impedance (dielectric layer) HTC 100µm	0,33 (0,051)**	Kcm²/W (Kin²/W)	ASTM D5470
Dielectric breakdown voltage, (AC)	≥4	kV/100µm dielectric layer	IPC TM 650 2.5.6.3
Flammability, according UL-94, class	V-0	class	UL-94
Glass transition temperature of dielectric layer (byTMA)	>180	°C	IPC-TM 650-2.4.24
Decomposition Temperature (Td) Initial	340	°C	IPC-TM 650-2.3.41
Decomposition Temperature (Td) 5% loss	420	°C	IPC-TM 650-2.3.41
Thermal delamination (Td) T 260	>80	min	IPC-TM 650-2.4.24.1
Thermal delamination (Td) T 288	>80	min	IPC-TM 650-2.4.24.1
Thermal delamination (Td) T 300	>80	min	IPC-TM 650-2.4.24.1
CTE (x,y)	14-15	ppm/°C	IPC-TM 650-2.4.41
CTE (z) <tg< td=""><td>37</td><td>ppm/°C</td><td>IPC-TM 650-2.4.24</td></tg<>	37	ppm/°C	IPC-TM 650-2.4.24
CTE (z) >Tg	172	ppm/°C	IPC-TM 650-2.4.24
Z-axis Expansion (50-250°C)	1.8 (77ppm)	%	IPC-TM 650-2.4.24

⁽¹⁾ Pressed under vacuum, temperature and pressure (see cycle below), between thick aluminium sheet (alloy 5052), and ED copper foil 70µm (**) Thermal Conductivity and Impedance values may have a +/- 15% deviation.



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Store preferably in the original unopened package or sealed by tape. Keep storage climate conditions below 24°C and 55% relative humidity. In the event of storing

under very low warehouse temperatures give some time for the packed prepreg to stabilize to room temperature before opening. Keeping the above mentioned storage conditions and avoiding prepreg damage by humidity uptake will give a useful life of 3 months after production date.

Resin and prepreg parameters have been adjusted for low flow performance. This means they are suitable for heating rates around 3 to 7°C/min, and specific pressures

between 18-22 bars. Vacuum applied during press cycle is mandatory for optimal performance. Use of synthetic thermal resistance pads should be test choice. Curing

The data is based on typical values of standard production and should be considered as general information. Our company reserves the right to future changes.

Aluminium is supplied with mechanical treatment and special primer in order to guarantee the correct adherence in the ML process.